

VERSION SHOWING THE CHANGES TO THE CLAIMS

This listing replaces all prior listings.

IN THE CLAIMS

Amend the claims as follows:

Claim 1, canceled.

2 (Currently amended). The electronic component as set forth in claim 13 4 wherein the through plating has a cross-sectional profile ~~which of the through plating~~ comprises a truncated conical cross section free-standing raised portion relative to the first layer of electrically conductive or non-conductive material.

3 (Currently amended). The electronic component as set forth in claim 13 2 wherein the through plating comprises a truncated conical cross section profile free-standing raised portion of electrically conductive material and includes polyaniline, pedot, carbon black, graphite, electrically conducting silver and/or metal and/or a mixture thereof.

4 (Currently amended). The electronic component as set forth in claim 13 2 wherein the component includes including a an electrically non-conducting insulating material wherein at least one of the plurality of layers central functional layer and the non-conducting material is includes an insulating material selected from the group consisting of such as polyhydroxystyrene, polymethylmethacrylate and/or polystyrene and/or a semiconducting material including such as polyalkylthiophene and/or

polyfluorene and/or a mixture thereof.

5(Currently amended). The electronic component as set forth in claim 13 4 wherein the through-plating comprises ~~is in the form of~~ a raised portion relative to the first layer that has a surface roughness which promotes ohmic contacting.

6(Currently amended). The electronic component as set forth in claim 13 ~~one of the preceding claims wherein the cross-sectional profile~~ the disruption element manifests shows a chemical treatment at least of the first ~~a lower functional layer~~ .

7(Currently amended). The electronic component as set forth in claim 13 ~~one claims 1-5 wherein the first layer comprises a lower functional layer wherein the disruption element cross-sectional profile~~ manifests shows a physical treatment of at least the ~~a lower functional layer~~ .

8(Currently amended). The electronic component as set forth in one of claims 1-5 wherein the first layer comprises a lower functional organic layer ~~wherein the cross-sectional profile shows a local disruption location on the at least one lower functional layer.~~

9(Currently amended). The electronic component as set forth in one of claims 1-5 wherein the first layer comprises an organic functional layer wherein the disruption element ~~the cross-sectional profile manifests a~~ shows a preceding locally

restricted change in the surface energy of the ~~at least one lower~~ first organic functional layer, at which substantially no wetting by a subsequently applied organic material of a subsequent ~~central~~ functional layer is present occurred.

10(Currently amended). The electronic component as set forth in ~~one of claims~~ 1-5 claim 13 wherein a the disruption location element is ~~produced locally~~ on the ~~at least one~~ first lower functional layer and comprises a chemical ~~chemically by~~ ~~application of a material~~ which provides a material residue on the first layer, at which prior to or after application of ~~one of the plurality of central functional layers~~, the disruption element ~~dislocation is detectable~~ can be detected by at least one of a material residue[[s]], the shape of the disruption element location, ~~and/or~~ traces or a material on the first ~~at least one lower functional~~ layer .

11(Currently amended). The electronic component as set forth in claim 13 ~~one of claims 1-5~~ wherein the component comprises ~~is made up of~~ a plastic substrate which includes one of the following materials: PET, PP, PEN, polyimide, polyamide and ~~and/or~~ coated paper.

12(Currently amended). A process for the production of at least one through-plating of an electronic component comprising:

forming a plurality of layers, a majority of which layers are of predominantly organic material and include ~~and~~ an insulating layer, the forming of a first lower layer being followed by forming subsequent layers deposited sequentially on the first layer.

the forming of the first layer including forming a disruption element on the first layer
which element is arranged to result in a void in at least a first portion of the
subsequently deposited layers, and then forming a through plating in the resulting void
wherein at least a second portion of layers are ohmically intercoupled by the through
plating, wherein the through plating is formed prior to application of the insulating layer.

13(Currently amended). An electronic product comprising:

a first layer;

a disruption element on a portion of the first layer over a given region of the first

layer;

a plurality of layers on the first layer and overlying the disruption element on the
first layer, at least a first portion of the plurality of layers comprises predominantly
organic material;

the disruption element being arranged to result in a void in a second portion of
the plurality of layers in the area above the disruption element; and

a through plating in the resulting void for forming an electrical interconnection to
at least two of the layers ~~The use of the component as set forth in one of claims 1-~~
~~through 5 in an electronic product.~~

Add the following claims:

14 (New). The component of claim 13 wherein the through plating has a truncated conical cross section profile.

15 (New). The component of claim 13 wherein the through plating has a truncated conical cross section profile and is solid.

16(New). The component of claim 13 wherein the through plating has a truncated conical cross section profile and is hollow.

17 (New). An electronic component comprising:

a plurality of layers including a plurality of predominately organic functional layers at least one of which layers is a lower layer and at least one other of the layers is a central layer; and

at least one through plating having a truncated conical cross-sectional profile which extends from the lower layer through at least the central layer transversely to the central layer and which truncated conical through plating extends at least in part below the at least one central functional layer and is coupled to at least two of said plurality of layers.

18 (New). The component of claim 17 wherein the through plating is electrically conductive and is ohmically coupled to the at least two layers.

19 (New). The component of claim 17 wherein the plurality of layers are on the lower layer and form upper layers, the through-plating extending from the lower layer through at least one upper layer.

20 (New). The component of claim 17 wherein the through plating is electrically conductive.

21 (New). The component of claim 17 wherein the through plating decreases in diameter as it extends away from a lower layer to an upper layer.

22 (New). The component of claim 17 wherein the through plating extends through each of a plurality of layers different than the lower layer and is coupled to each of the plurality of layers through which it extends.

23 (New). The component of claim 17 wherein the through plating extends through each of a plurality of layers different than the lower layer and is coupled to the plurality of layers through which it extends, the through plating being electrically conductive and at least two of said layers to which the through plating is coupled are electrically conductive and in ohmic contact with the through plating.

24 (New). The component of claim 17 wherein the through plating is one of solid and hollow.